

ANTREX Electronics

Electronic Components Sourcing Information

Product Reference Information

Part Number:	TC1321EOA
Manufacturer:	Microchip Technology
Package:	8-SOIC (0.154" , 3.90mm Width)
Availability:	Please confirm with sales

Product Page:

<https://antrexco.com/product/details/microchip-technology/tc1321eoa.html>

Request a Quote:

[Submit RFQ for this part](#)



Scan for product page

Contact Information

Email: info@antrexco.com

WhatsApp: +86-186-8066-5326

Website: <https://antrexco.com>

Quality & Trust

New & Original Components

Supplier verification and packaging condition review

CoC / RoHS / REACH documents available on request

Secure sourcing support for OEM / EMS projects

Note:

This PDF includes an ANTREX product reference cover page.

The original manufacturer datasheet follows from the next page.

10-Bit Digital-to-Analog Converter with Two-Wire Interface

Features

- 10-Bit Digital-to-Analog Converter
- 2.7-5.5V Single Supply Operation
- Simple SMBus/I²C™ Serial Interface
- Low Power Operation
 - Normal Mode: 350 μ A
 - Shutdown Mode: 0.5 μ A
- Temperature Range: 40°C to +85°C
- 8-Pin SOIC and 8-Pin MSOP Packages

Applications

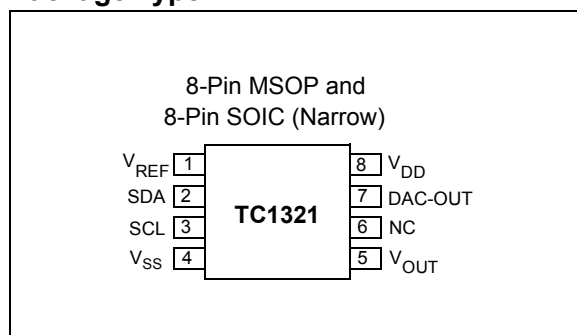
- Programmable Voltage Sources
- Digital Controlled Amplifiers/Attenuators
- Process Monitoring and Control

General Description

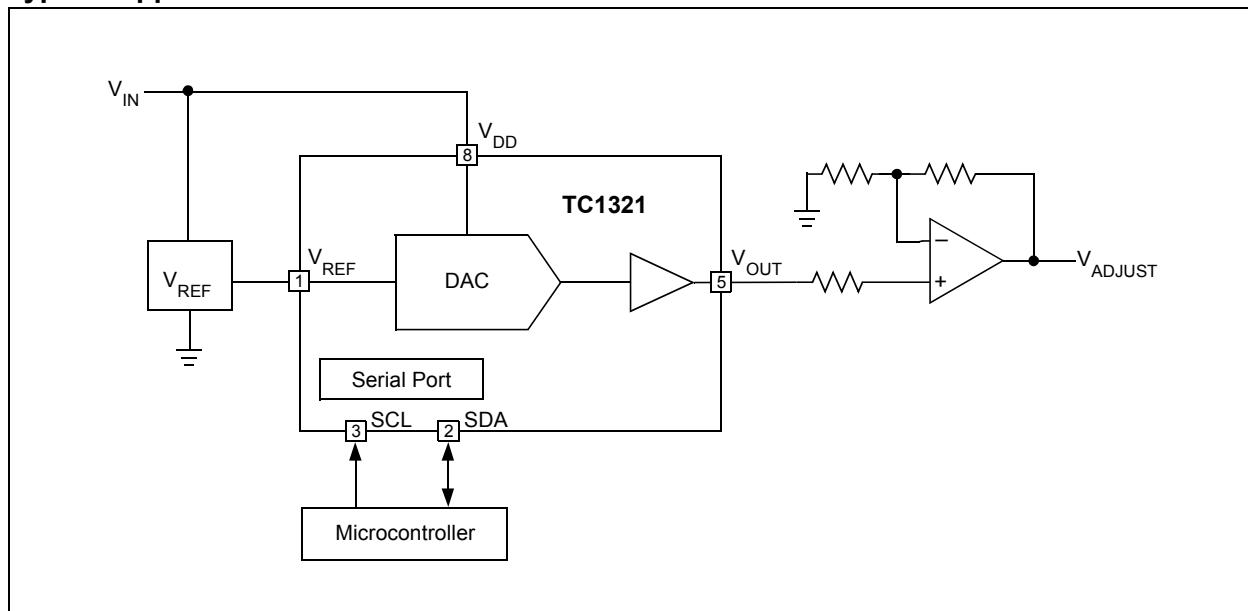
The TC1321 is a serially accessible, 10-bit voltage output, digital-to-analog converter (DAC). The DAC produces an output voltage that ranges from ground to an externally supplied reference voltage. It operates from a single power supply that can range from 2.7V to 5.5V, making it ideal for a wide range of applications. Built into the part is a Power-on Reset (POR) function that ensures that the device starts at a known condition.

Communication with the TC1321 is accomplished via a simple 2-wire SMBus/I²C compatible serial port, with the TC1321 acting as a slave only device. The host can enable the SHDN bit in the CONFIG register to activate the Low Power Standby mode.

Package Type

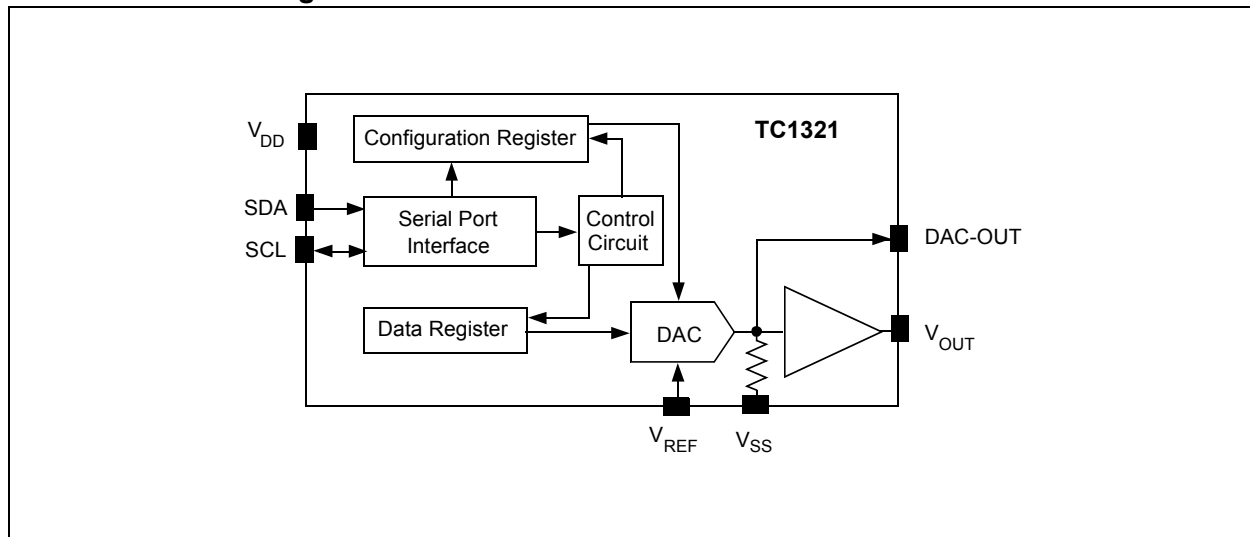


Typical Application



TC1321

Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Supply Voltage (V_{DD})	+6V
Voltage on any Pin	($V_{SS} - 0.3V$) to ($V_{DD} + 0.3V$)
Current on any Pin	± 50 mA
Package Thermal Resistance (θ_{JA})	330°C C/W
Operating Temperature (T_A)	See Below
Storage Temperature (T_{STG})	-65°C to +150°C

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

ELECTRICAL SPECIFICATIONS

Electrical Characteristics: $V_{DD} = 2.7V$ to $5.5V$, $-40^\circ C \leq T_A \leq +85^\circ C$, $V_{REF} = 1.2V$ unless otherwise noted.						
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
Power Supply						
V_{DD}	Supply Voltage	2.7	—	5.5	V	
I_{DD}	Operating Current	—	350	500	μA	$V_{DD} = 5.5V$, $V_{REF} = 1.2V$ Serial Port Inactive (Note 1)
I_{DD-} STANDBY	Standby Supply Current	—	0.1	1	μA	$V_{DD} = 3.3V$ Serial Port Inactive (Note 1)
Static Performance - Analog Section						
	Resolution	—	—	10	Bits	
INL	Integral Non-Linearity at FS, $T_A = +25^\circ C$	—	—	± 4.0	LSB	(Note 2)
FSE	Full Scale Error	—	—	± 3	%FS	
DNL	Differential Non-Linearity, $T_A = +25^\circ C$	-1	—	+2	LSB	All Codes (Note 2)
V_{OS}	Offset Error at V_{OUT}	—	± 0.3	± 8	mV	(Note 2)
TCV_{OS}	Offset Error Tempco at V_{OUT}	—	10	—	$\mu V/^\circ C$	
PSRR	Power Supply Rejection Ratio	—	80	—	dB	V_{DD} at DC
V_{REF}	Voltage Reference Range	0	—	$V_{DD} - 1.2$	V	
I_{REF}	Reference Input Leakage Current	—	—	± 1.0	μA	
V_{SW}	Voltage Swing	0	—	V_{REF}	V	$V_{REF} \leq (V_{DD} - 1.2V)$
R_{OUT}	Output Resistance @ V_{OUT}	—	5.0	—	Ω	$R_{OUT} (\Omega)$
I_{OUT}	Output Current (Source or Sink)	—	2	—	mA	
I_{SC}	Output Short-Circuit Current $V_{DD} = 5.5V$	— —	30 20	50 50	mA mA	Source Sink
Dynamic Performance						
SR	Voltage Output Slew Rate	—	0.8	—	V/ μs	
t_{SETTLE}	Output Voltage Full Scale Settling Time	—	10	—	μs	
t_{WU}	Wake-up Time	—	20	—	μs	
	Digital Feed Through and Crosstalk	—	5	—	nV-s	SDA = V_{DD} , SCL = 100 kHz
Serial Port Interface						
V_{IH}	Logic Input High	2.4	—	V_{DD}	V	
V_{IL}	Logic Input Low	—	—	0.6	—	
V_{OL}	SDA Output Low	— —	— —	0.4 0.6	V V	$I_{OL} = 3$ mA (Sinking Current) $I_{OL} = 6$ mA

- Note 1:** SDA and SCL must be connected to V_{DD} or V_{SS} .
Note 2: Measured at $V_{OUT} \geq 50$ mV referred to V_{SS} to avoid output buffer clipping.

ELECTRICAL SPECIFICATIONS (CONTINUED)

Electrical Characteristics: $V_{DD} = 2.7V$ to $5.5V$, $-40^{\circ}C \leq T_A \leq +85^{\circ}C$, $V_{REF} = 1.2V$ unless otherwise noted.						
Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
C_{IN}	Input Capacitance (SDA and SCL pins)	—	5	0.4	pF	
I_{LEAK}	I/O Leakage	—	—	± 1.0	μA	
Serial Port AC Timing						
f_{SMB}	SMBus Clock Frequency	10	—	100	kHz	
t_{IDLE}	Bus Free Time Prior to New Transition	4.7	—	—	μs	
$t_{H(START)}$	START Condition Hold Time	4.0	—	—	μs	
$t_{SU(START)}$	START Condition Setup Time	4.7	—	—	μs	90% SCL to 10% SDA (for Repeated START Condition)
$t_{SU(STOP)}$	STOP Condition Setup Time	4.0	—	—	μs	
t_{H-DATA}	Data In Hold Time	100	—	—	ns	
$t_{SU-DATA}$	Data In Setup Time	100	—	—	ns	
t_{LOW}	Low Clock Period	4.7	—	—	μs	10% to 10%
t_{HIGH}	High Clock Period	4	—	—	μs	90% to 90%
t_F	SMBus Fall Time	—	—	300	ns	90% to 10%
t_R	SMBus Rise Time	—	—	1000	ns	10% to 90%
t_{POR}	Power-on Reset Delay	—	500	—	μs	$V_{DD} \geq V_{POR}$ (Rising Edge)

Note 1: SDA and SCL must be connected to V_{DD} or V_{SS} .

Note 2: Measured at $V_{OUT} \geq 50$ mV referred to V_{SS} to avoid output buffer clipping.

TEMPERATURE CHARACTERISTICS

Electrical Specifications: $V_{DD} = 2.7V$ to $5.5V$, $-40^{\circ}C \leq T_A \leq +85^{\circ}C$, $V_{REF} = 1.2V$ unless otherwise noted.						
Parameters	Symbol	Min	Typ	Max	Units	Conditions
Temperature Ranges						
Operating Temperature Range	T_A	-40	—	+85	$^{\circ}C$	
Storage Temperature Range	T_A	-65	—	150	$^{\circ}C$	
Thermal Package Resistances						
Thermal Resistance, 8L SOIC	θ_{JA}	—	149.5	—	$^{\circ}C/W$	
Thermal Resistance, 8L MSOP	θ_{JA}	—	211	—	$^{\circ}C/W$	

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 2-1](#).

TABLE 2-1: PIN FUNCTION TABLE

Pin Number	Pin Name	Type	Description
1	V _{REF}	Input	Voltage Reference Input Pin
2	SDA	Bi-Directional	Serial Data Input/Output Pin
3	SCL	Input	Serial Clock Input Pin
4	V _{SS}	Power	Ground Reference Pin
5	V _{OUT}	Output	Buffered Analog Voltage Output Pin
6	NC	None	No connection
7	DAC-OUT	Output	Unbuffered Analog Voltage Output Pin
8	V _{DD}	Power	Positive Power Supply Input Pin

2.1 External Voltage Reference Input (V_{REF})

Voltage Reference Input can range from 0V to 1.2V below V_{DD}.

2.2 Bi-Directional Serial Data Input and Output (SDA)

Serial data is transferred on the SMBus in both directions using this pin.

2.3 Serial Clock Input (SCL)

SMBus/I²C serial clock. Clocks data into and out of the TC1321.

2.4 Supply Power Ground (V_{SS})

The ground reference pin.

2.5 Output (V_{OUT})

Buffered DAC output voltage. This voltage is a function of the reference voltage and the contents of the DATA register.

2.6 No Connection (NC)

There is not a connection at this pin.

2.7 Output (DAC-OUT)

Unbuffered DAC output voltage. This voltage is a function of the reference voltage and the contents of the DATA register. This output is unbuffered and care must be taken that the pin is connected only to a high-impedance node.

2.8 Positive Power Supply Input (V_{DD})

See the [Electrical Specifications](#) table.

NOTES:

3.0 DETAILED DESCRIPTION

The TC1321 is a monolithic 10-bit digital-to-analog converter that is designed to operate from a single supply that can range from 2.7V to 5.5V. The DAC consists of a data register (DATA), a configuration register (CONF), and a current output amplifier. The TC1321 uses an external reference which also determines the maximum output voltage.

The TC1321 uses a current steering DAC based on an array of matched current sources. This current, along with a precision resistor, converts the contents of the DATA Register and V_{REF} into an output voltage, V_{OUT} , that is given by:

$$V_{OUT} = V_{REF} \times \left[\frac{DATA}{1024} \right]$$

3.1 Reference Input

The reference pin, V_{REF} , is a buffered high-impedance input. Because of this, the load regulation of the reference source needs only to be able to tolerate leakage levels of current (less than 1 μ A). V_{REF} accepts a voltage range from 0 to ($V_{DD} - 1.2V$). Input capacitance is typically 10 pF.

3.2 Output Amplifier

The TC1321 DAC output is buffered with an internal unity gain rail-to-rail input/output amplifier with a typical slew rate of 0.8V/ μ s. Maximum full scale transition settling time is 10 μ sec to within $\pm 1/2$ LSB when loaded with 1 k Ω in parallel with 100 pF.

3.3 Standby Mode

The TC1321 allows the host to put it into a Low Power ($I_{DD} = 0.5 \mu$ A, typically) Standby mode.

In this mode, the D/A conversion is halted. The SMBus port operates normally. Standby mode is enabled by setting the SHDN bit in the CONFIG register. [Table 3-1](#) summarizes this operation.

TABLE 3-1: STANDBY MODE OPERATION

SHDN Bit	Operating Mode
0	Normal
1	Standby

3.4 SMBus Slave Address

The TC1321 is internally programmed to have a default SMBus address value of 1001 000b. Seven other addresses are available by custom order (contact Microchip [Worldwide Sales and Service](#)). See [Figure 3-1](#) for the location of address bits in SMBus protocol.

Write 1-Byte Format

S	Address	R/W	ACK	Command	ACK	Data	ACK	P
	7-Bits	0		8-Bits		8-Bits		

Slave Address

Command Byte: selects which register you are writing to.

Data Byte: data goes into the register set by the command byte.

Write 2-Byte Format

S	Address	R/W	ACK	Command	ACK	Data	ACK	Data	ACK	P
	7-Bits	0		8-Bits		8-Bits		8-Bits		

Slave Address

Command Byte: selects which register you are writing to.

Data Byte: data goes into the register set by the command byte.

Read 1-Byte Format

S	Address	R/W	ACK	Command	ACK	S	Address	R/W	ACK	Data	NACK	P
	7-Bits	0		8-Bits			7-Bits	1		8-Bits		

Slave Address

Command Byte: selects which register you are reading from.

Slave Address: repeated due to change in data flow direction.

Data Byte: reads from the register set by the command byte.

Read 2-Byte Format

S	Address	R/W	ACK	Command	ACK	S	Address	R/W	ACK	Data	ACK	Data	NACK	P
	7-Bits	0		8-Bits			7-Bits	1		8-Bits		8-Bits		

Slave Address

Command Byte: selects which register you are reading from.

Slave Address: repeated due to change in data flow direction.

Data Byte: reads from the register set by the command byte.

Receive 1-Byte Format

S	Address	R/W	ACK	Data	NACK	P
	7-Bits	1		8-Bits		

S = START Condition

P = STOP Condition

Shaded = Slave Transmission

Data Byte: reads data from the register commanded by the last read-byte or write-byte transmission.

Receive 1-Byte Format

S	Address	R/W	ACK	Data	ACK	Data	NACK	P
	7-Bits	1		8-Bits		8-Bits		

S = START Condition

P = STOP Condition

Shaded = Slave Transmission

Data Byte: reads data from the register commanded by the last read-byte or write-byte transmission.

FIGURE 3-1: SMBus/I²C Protocols.

4.0 SERIAL PORT OPERATION

The Serial Clock input (SCL) and bi-directional data port (SDA) form a 2-wire bi-directional serial port for programming and interrogating the TC1321. The following conventions are used in this bus architecture.

TABLE 4-1: TC1321 SERIAL BUS CONVENTIONS

Term	Explanation
Transmitter	The device sending data to the bus.
Receiver	The device receiving data from the bus.
Master	The device that controls the bus: initiating transfers (START), generating the clock, and terminating transfers (STOP)
Slave	The device addressed by the master.
START	A unique condition signaling the beginning of a transfer, indicated by SDA falling (High - Low) while SCL is high.
STOP	A unique condition signaling the end of a transfer, indicated by SDA rising (Low - High) while SCL is high.
ACK	A receiver acknowledges the receipt of each byte with this unique condition. The receiver drives SDA low during SCL, high of the ACK clock pulse. The master provides the clock pulse for the ACK cycle.
Busy	Communication is not possible because the bus is in use.
Not Busy	When the bus is IDLE, both SDA and SCL will remain high.
Data Valid	The state of SDA must remain stable during the High period of SCL in order for a data bit to be considered valid. SDA only changes state while SCL is low during normal data transfers. See START and STOP conditions.

All transfers take place under control of a host, usually a CPU or microcontroller, acting as the master, which provides the clock signal for all transfers. The TC1321 *always* operates as a slave. The serial protocol is illustrated in [Figure 4-1](#). All data transfers have two phases; all bytes are transferred MSB first. Accesses are initiated by a START condition (START), followed by a device-address byte and one or more data bytes. The device-address byte includes a Read/Write selection bit. Each access must be terminated by a STOP Condition (STOP). A convention called *Acknowledge* (ACK) confirms receipt of each byte. Note that SDA can change only during periods when SCL is LOW (SDA changes while SCL is HIGH are reserved for START and STOP conditions).

4.1 START Condition (START)

The TC1321 continuously monitors the SDA and SCL lines for a START condition (a HIGH to LOW transition of SDA while SCL is HIGH), and will not respond until this condition is met.

4.2 Address Byte

Immediately following the START condition, the host must transmit the address byte to the TC1321. The 7-bit SMBus address for the TC1321 is 1001000. The 7-bit address transmitted in the serial bit stream must match for the TC1321 to respond with an Acknowledge (indicating the TC1321 is on the bus and ready to accept data). The eighth bit in the Address Byte is a Read-Write bit. This bit is a 1 for a read operation or 0 for a write operation. During the first phase of any transfer, this bit will be set = 0 to indicate that the command byte is being written.

4.3 Acknowledge (ACK)

Acknowledge (ACK) provides a positive handshake between the host and the TC1321. The host releases SDA after transmitting eight bits, then generates a ninth clock cycle to allow the TC1321 to pull the SDA line LOW to Acknowledge that it successfully received the previous eight bits of data or address.

4.4 Data Byte

After a successful ACK of the address byte, the host must transmit the data byte to be written or clock out the data to be read. (See the appropriate timing diagrams.) ACK will be generated after a successful write of a data byte into the TC1321.

4.5 Stop Condition (STOP)

Communications must be terminated by a STOP condition (a LOW to HIGH transition of SDA while SCL is HIGH). The STOP condition must be communicated by the transmitter to the TC1321. Refer to [Figure 4-1](#), for serial bus timing.

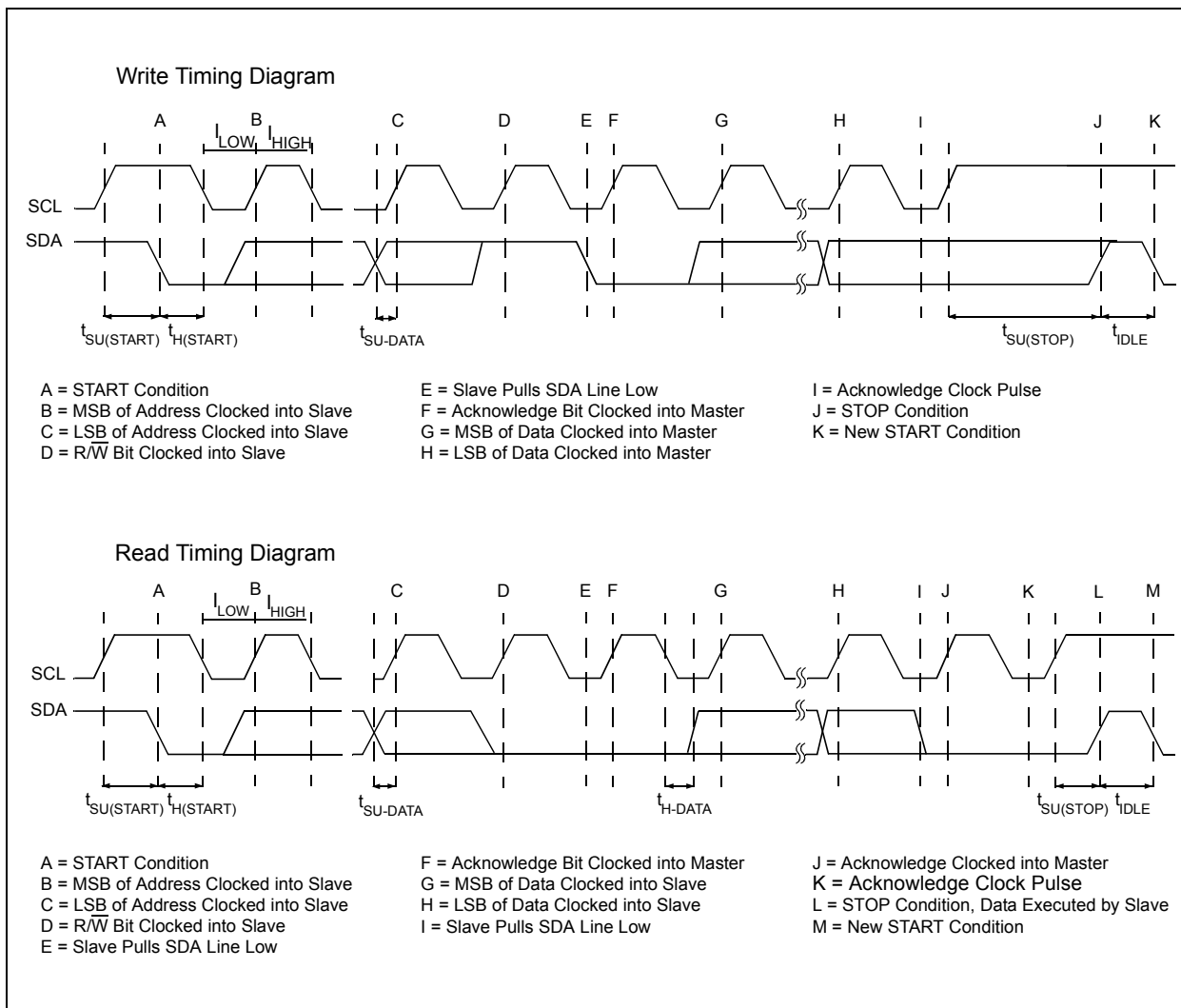


FIGURE 4-1: SMBus/I²C Timing Diagrams.

4.6 Register Set and Programmer's Model

TABLE 4-2: TC1321 COMMAND SET (READ_BYTE AND WRITE_BYTE)

Command Byte Description		
Command	Code	Function
RWD	00h	Read/Write Data (DATA)
RWCR	01h	Read/Write Configuration (CONFIG)

TABLE 4-3: CONFIGURATION REGISTER (CONFIG), 8-BIT, READ/WRITE

Configuration Register (CONFIG)								
Bit Name	D[7]	D[6]	D[5]	D[4]	D[3]	D[2]	D[1]	D[0]
Bit Function	Reserved (Note 1)							SHDN (Note 2)

Note 1: Always returns '0' when reading
Note 2: 1 = Standby (Shut down) mode
 0 = Normal mode

TABLE 4-4: DATA REGISTER (DATA), 10-BIT, READ/WRITE

Data Register (DATA) for 1st Byte								Data Register (DATA) for 2nd Byte							
D[9]	D[8]	D[7]	D[6]	D[5]	D[4]	D[3]	D[2]	D[1]	D[0]	X	X	X	X	X	X
MSB	X	X	X	X	X	X	X	X	LSB	X	X	X	X	X	X

The DAC output voltage is a function of reference voltage and the binary value of the contents of the register DATA. The transfer function is given by the expression:

EQUATION 4-1:

$$V_{OUT} = V_{REF} \times \left[\frac{DATA}{1024} \right]$$

4.7 Register Set Summary

The register set for the TC1321 is summarized in [Table 4-5](#).

TABLE 4-5: TC1321 REGISTER SET SUMMARY

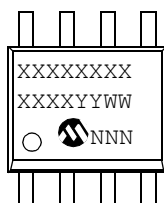
Name	Description	POR State	Read	Write
Data	DATA Register (2-Byte Format)	0000000000b	X	X
Config	CONFIG Register	0000 0000b	X	X

NOTES:

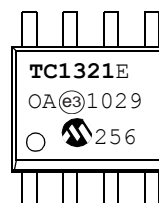
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

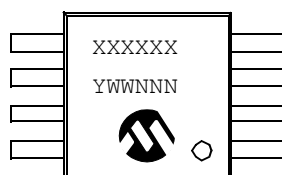
8-Lead SOIC (150 mil)



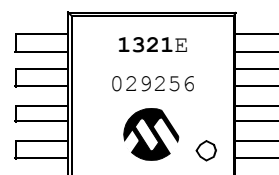
Example



8-Lead MSOP



Example



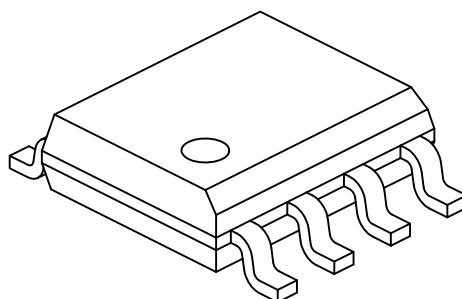
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.	

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging
--------------	--



8-Lead Plastic Small Outline (OA) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E	6.00 BSC		
Molded Package Width	E1	3.90 BSC		
Overall Length	D	4.90 BSC		
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1	1.04 REF		
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

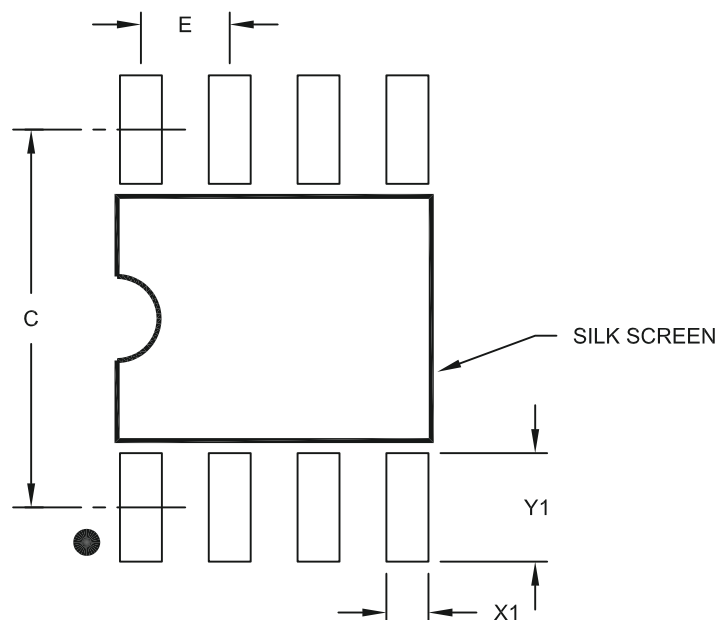
Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing No. C04-057C Sheet 2 of 2

8-Lead Plastic Small Outline (OA) – Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

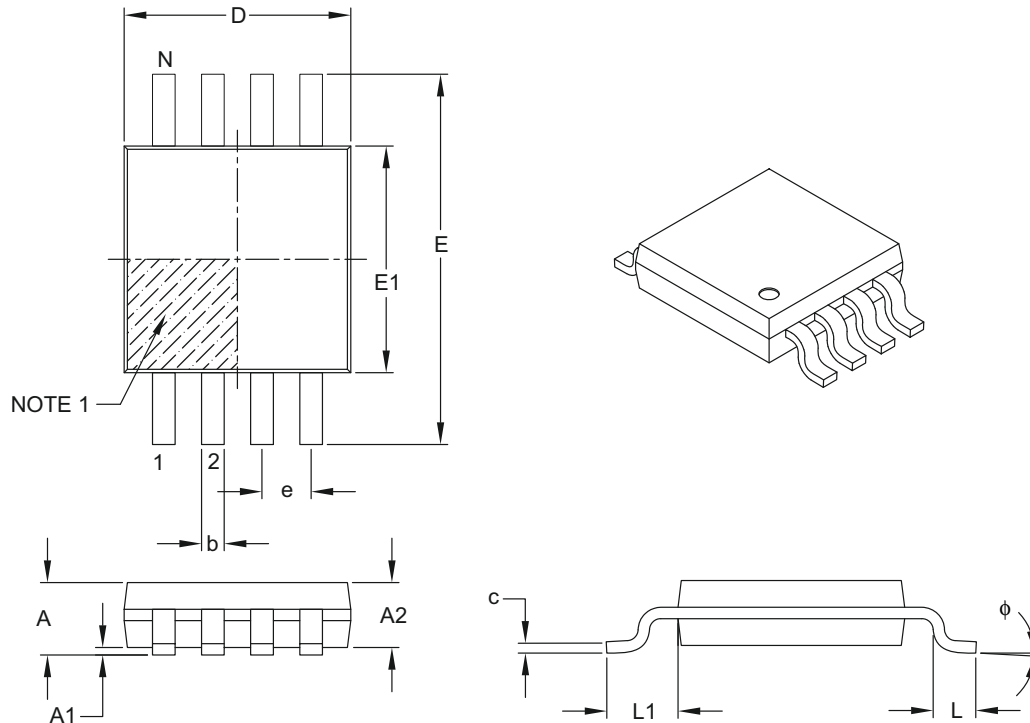
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2057A

8-Lead Plastic Micro Small Outline Package (UA) [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.65 BSC		
Overall Height	A	–	–	1.10
Molded Package Thickness	A2	0.75	0.85	0.95
Standoff	A1	0.00	–	0.15
Overall Width	E	4.90 BSC		
Molded Package Width	E1	3.00 BSC		
Overall Length	D	3.00 BSC		
Foot Length	L	0.40	0.60	0.80
Footprint	L1	0.95 REF		
Foot Angle	φ	0°	–	8°
Lead Thickness	c	0.08	–	0.23
Lead Width	b	0.22	–	0.40

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

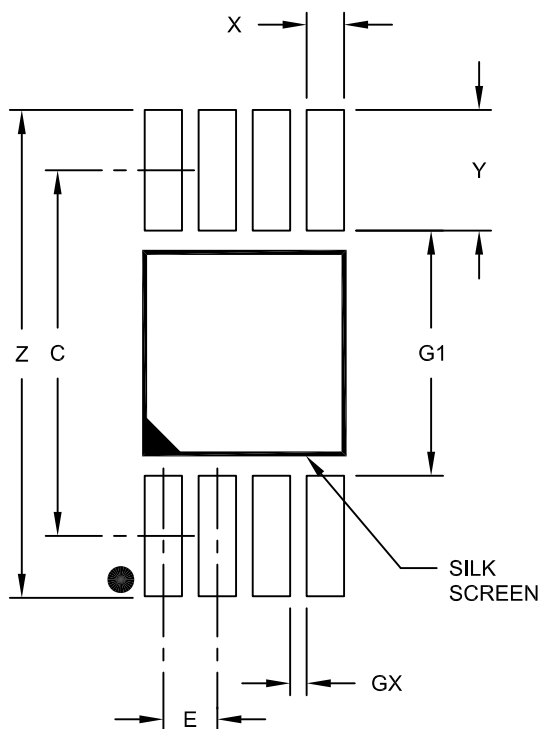
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-111B

8-Lead Plastic Micro Small Outline Package (UA) [MSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Contact Pad Spacing	C		4.40	
Overall Width	Z			5.85
Contact Pad Width (X8)	X1			0.45
Contact Pad Length (X8)	Y1			1.45
Distance Between Pads	G1	2.95		
Distance Between Pads	GX	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2111A

APPENDIX A: REVISION HISTORY

Revision C (November 2010)

The following is the list of modifications:

1. Updated the Electrical Specifications table.
2. Updated **Section 5.0 “Packaging Information”**. Replaced the older package drawings with current drawings from the *Microchip Packaging Specification* (DS00049BF).
3. Added the Revision History section.
4. Updated the Product Identification System section.

Revision B (May 2008)

- Undocumented changes.

Revision A (November 2007)

- Original Release of this Document.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>		<u>X</u>	<u>/XX</u>	<u>XXX</u>
Device	Temperature Range		Package	Pattern
Device	TC1321: 10-Bit Digital-to-Analog Converter with Two-Wire Interface			
Tape and Reel	TR	=	Tape and Reel	
Temperature Range	I	=	-40°C to +85°C (Industrial)	
Package	OA	=	Small Outline Package (SOIC), (3,90 mm) 8-lead	
	UA	=	Micro Small Outline Package (MSOP), 8-lead	

Examples:

a) TC1321VUA: 8LD MSOP package.

b) TC1321VUATR: Tape and Reel 8LD MSOP package.

c) TC1321EUA: 8LD MSOP package.

d) TC1321EUATR: Tape and Reel, 8LD MSOP package.

e) TC1321EOA: 8LD SOIC package.

f) TC1321EOATR: Tape and Reel 8LD SOIC package.

g) TC1321VOA: 8LD SOIC package.

h) TC1321VOATR: Tape and Reel 8LD SOIC package.

NOTES:

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscent Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICTail, REAL ICE, rLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2010, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

 Printed on recycled paper.

ISBN: 978-1-60932-567-1

QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
== ISO/TS 16949:2002 ==

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

Worldwide Sales and Service

AMERICAS

Corporate Office
2355 West Chandler Blvd.
Chandler, AZ 85224-6199
Tel: 480-792-7200
Fax: 480-792-7277
Technical Support:
<http://support.microchip.com>
Web Address:
www.microchip.com

Atlanta
Duluth, GA
Tel: 678-957-9614
Fax: 678-957-1455

Boston
Westborough, MA
Tel: 774-760-0087
Fax: 774-760-0088

Chicago
Itasca, IL
Tel: 630-285-0071
Fax: 630-285-0075

Cleveland
Independence, OH
Tel: 216-447-0464
Fax: 216-447-0643

Dallas
Addison, TX
Tel: 972-818-7423
Fax: 972-818-2924

Detroit
Farmington Hills, MI
Tel: 248-538-2250
Fax: 248-538-2260

Kokomo
Kokomo, IN
Tel: 765-864-8360
Fax: 765-864-8387

Los Angeles
Mission Viejo, CA
Tel: 949-462-9523
Fax: 949-462-9608

Santa Clara
Santa Clara, CA
Tel: 408-961-6444
Fax: 408-961-6445

Toronto
Mississauga, Ontario,
Canada
Tel: 905-673-0699
Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office
Suites 3707-14, 37th Floor
Tower 6, The Gateway
Harbour City, Kowloon
Hong Kong
Tel: 852-2401-1200
Fax: 852-2401-3431

Australia - Sydney
Tel: 61-2-9868-6733
Fax: 61-2-9868-6755

China - Beijing
Tel: 86-10-8528-2100
Fax: 86-10-8528-2104

China - Chengdu
Tel: 86-28-8665-5511
Fax: 86-28-8665-7889

China - Chongqing
Tel: 86-23-8980-9588
Fax: 86-23-8980-9500

China - Hong Kong SAR
Tel: 852-2401-1200
Fax: 852-2401-3431

China - Nanjing
Tel: 86-25-8473-2460
Fax: 86-25-8473-2470

China - Qingdao
Tel: 86-532-8502-7355
Fax: 86-532-8502-7205

China - Shanghai
Tel: 86-21-5407-5533
Fax: 86-21-5407-5066

China - Shenyang
Tel: 86-24-2334-2829
Fax: 86-24-2334-2393

China - Shenzhen
Tel: 86-755-8203-2660
Fax: 86-755-8203-1760

China - Wuhan
Tel: 86-27-5980-5300
Fax: 86-27-5980-5118

China - Xian
Tel: 86-29-8833-7252
Fax: 86-29-8833-7256

China - Xiamen
Tel: 86-592-2388138
Fax: 86-592-2388130

China - Zhuhai
Tel: 86-756-3210040
Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore
Tel: 91-80-3090-4444
Fax: 91-80-3090-4123

India - New Delhi
Tel: 91-11-4160-8631
Fax: 91-11-4160-8632

India - Pune
Tel: 91-20-2566-1512
Fax: 91-20-2566-1513

Japan - Yokohama
Tel: 81-45-471- 6166
Fax: 81-45-471-6122

Korea - Daegu
Tel: 82-53-744-4301
Fax: 82-53-744-4302

Korea - Seoul
Tel: 82-2-554-7200
Fax: 82-2-558-5932 or
82-2-558-5934

Malaysia - Kuala Lumpur
Tel: 60-3-6201-9857
Fax: 60-3-6201-9859

Malaysia - Penang
Tel: 60-4-227-8870
Fax: 60-4-227-4068

Philippines - Manila
Tel: 63-2-634-9065
Fax: 63-2-634-9069

Singapore
Tel: 65-6334-8870
Fax: 65-6334-8850

Taiwan - Hsin Chu
Tel: 886-3-6578-300
Fax: 886-3-6578-370

Taiwan - Kaohsiung
Tel: 886-7-213-7830
Fax: 886-7-330-9305

Taiwan - Taipei
Tel: 886-2-2500-6610
Fax: 886-2-2508-0102

Thailand - Bangkok
Tel: 66-2-694-1351
Fax: 66-2-694-1350

EUROPE

Austria - Wels
Tel: 43-7242-2244-39
Fax: 43-7242-2244-393

Denmark - Copenhagen
Tel: 45-4450-2828
Fax: 45-4485-2829

France - Paris
Tel: 33-1-69-53-63-20
Fax: 33-1-69-30-90-79

Germany - Munich
Tel: 49-89-627-144-0
Fax: 49-89-627-144-44

Italy - Milan
Tel: 39-0331-742611
Fax: 39-0331-466781

Netherlands - Drunen
Tel: 31-416-690399
Fax: 31-416-690340

Spain - Madrid
Tel: 34-91-708-08-90
Fax: 34-91-708-08-91

UK - Wokingham
Tel: 44-118-921-5869
Fax: 44-118-921-5820